

Amendments to the Specification

Please amend the paragraph beginning on line 22 of page 3 as follows:

The socket 110 in one embodiment of the invention is specially adapted to inhibit the radiation of electromagnetic emissions from the processor 120 to the environment. In typical applications, the heat sink 140 is formed of a heat-conductive substance, which in conventional systems is often anodized aluminum or some other metal. In the present invention, the socket perimeter 130 is configured to form an electrically conductive path to the heat sink 140. One manner of doing this is to remove any insulation material (such as oxidation or anodization) from both the heat sink 140 and the socket perimeter 130, and in addition (or instead) material may be added to either or both of the heat sink and the socket to assist electrical coupling. In some embodiments, an electrically conductive gasket 175 may be positioned on socket 110 and extending along at least a portion of socket perimeter 130. The gasket 175 as shown in Figure 2 is formed in four separate segments, which in this case are positioned and sized with gaps 176 between them.

Please amend the paragraph beginning on line 1 of page 5 as follows:

The gasket 210 in one embodiment is formed of a conductive polymer, which bonds to both the skirt 200 and the socket perimeter 130. Other conductive bonding materials may be used. The gasket as shown in Figure 3 is formed in four separate segments, which in this case are positioned and sized with gaps 211 between them. The sizes of the allowable intervening gaps will depend upon the frequency and power of the shielded device or devices, the expected field shape or structure, and the amount of desired attenuation of the electromagnetic radiation. Alternatively, a continuous or substantially continuous gasket may be used, or different numbers of segments may be formed.

Please amend the paragraph beginning on line 22 of page 5 as follows:

With this arrangement, it can be seen in Figure 4 that a substantially continuous electromagnetic shielding structure is formed by the heat sink 140, skirt 200, gasket 210, socket ~~110130~~ 110130, vias 300 and ground plane 310, which substantially surrounds the processor 100. The shielding is substantially continuous in the sense that, though there may be gaps in the effective enclosure formed by the electromagnetically shielding elements, there is a sufficient enclosure to attenuate electromagnetic signals at the relevant frequencies.